

SLOVENSKI STANDARD SIST EN 62317-9:2007

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Feritna jedra – Mere – 9. del: Planarna jedra (IEC 62317-9:2006)

Ferrite cores - Dimensions -- Part 9: Planar cores (IEC 62317-9:2006)

Ferritkerne - Maße -- Teil 9: Planarkerne (IEC 62317-9:2006)

Noyaux ferrites - Dimensions -- Partie 9: Noyaux planaires (IEC 62317-9:2006)

Ta slovenski standard je istoveten z:<u>TEN EN 62317</u>-9:2006

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<u>ICS:</u>

29.100.10 Magnetne komponente

Magnetic components

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EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

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English version

Ferrite cores -Dimensions Part 9: Planar cores (IEC 62317-9:2006)

Noyaux ferrites -Dimensions Partie 9: Noyaux planaires (CEI 62317-9:2006) Ferritkerne -Maße Teil 9: Planarkerne (IEC 62317-9:2006)

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CENELEC

European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 51/849/FDIS, future edition 1 of IEC 62317-9, prepared by IEC TC 51, Magnetic components and ferrite materials, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62317-9 on 2006-07-01.

This European Standard supersedes EN 61860:2000.

This European Standard includes the following significant changes and additions with respect to EN 61860:2000:

- a) addition of the planar EL family of cores;
- b) addition of the low-profile ER family of cores;
- c) the low-profile RM-family defined in EN 61860:2000 has been moved to EN 62317-4 for RM-cores and associated parts.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement
 (dop) 2007-04-01
- latest date by which the national standards conflicting with the EN have to be withdrawn CANDARD PREVIEW 2009-07-01

Annex ZA has been added by CENELECndards.iteh.ai)

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The text of the International Standard IEC 62317-9:2006 was approved by CENELEC as a European Standard without any modification.

EN 62317-9:2006

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	<u>EN/HD</u>	Year
IEC 60205	_1)	Calculation of the effective parameters of magnetic piece parts	EN 60205	2006 ²⁾
IEC 62317-4	2005	Ferrite cores - Dimensions Part 4: RM-cores and associated parts	EN 62317-4	2005

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¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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INTERNATIONAL STANDARD

IEC 62317-9

Edition 1.1 2007-03

Edition 1:2006 consolidated with amendment 1:2007

Ferrite cores – Dimensions –

Part 9: Planar cores

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Commission Electrotechnique Internationale International Electrotechnical Commission Международная Электротехническая Комиссия



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FERRITE CORES – DIMENSIONS –

Part 9: Planar cores

FOREWORD

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International Standard IEC 62317-9 has been prepared IEC technical committee 51: Magnetic components and ferrite materials.

This International Standard cancels and replaces IEC 61860 published in 2000. This edition constitutes a technical revision. This International Standard includes the following significant technical changes and additions with respect to IEC 61860:2000:

- a) addition of the planar EL family of cores;
- b) addition of the low-profile ER family of cores;
- c) the low-profile RM-family defined in IEC 61860:2000 has been moved to IEC 62137-4 for RM-cores and associated parts.

This consolidated version of IEC 62317-9 is based on the first edition (2006) [documents 51/849/FDIS and 51/858/RVD] and its amendment 1 (2007) [documents 51/866/CDV and 51/876/RVC].

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It bears the edition number 1.1.

A vertical line in the margin shows where the base publication has been modified by amendment 1.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

IEC 62317 consists of the following parts, under the general title Ferrite cores - Dimensions:

- Part 1: General (under consideration)
- Part 2: Pot cores (under consideration, currently available as IEC 60133)
- Part 3: Half pot cores (under consideration, currently available as IEC 62323)
- Part 4: RM-cores and associated parts
- Part 5: EP-cores (under consideration, currently available as IEC 61596)
- Part 6: ETD-cores (under consideration, currently available as IEC 61185)
- Part 7: EER-cores
- Part 8: E-cores
- Part 9: Planar corescent STANDARD PREVIEW
- Part 10: PM-cores (under consideration, currently available as IEC 61247)
- Part 11: EC-cores (under consideration, currently available as IEC 60647)

Part 12: Uncoated ring cores (under consideration, currently available as IEC 61604)

The committee has decided that the contents of the base publication and its amendments will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

Nowadays, d.c.-d.c. converter power supplies increasingly employ transformers and chokes the windings of which are made of multi-layer printed circuit board or the windings are constructed in the motherboard, rather than the transformers wound by conventional copper wires. This part of IEC 62317 specifies the optimum shapes and dimensions of cores for SMD (Surface Mounted Device) and of cores for which the windings are constructed in the motherboard has slots cut out to accept the ferrite cores. This is called the total integration in a multi-layer motherboard. The core shape specified in this part of IEC 62317 satisfies the demand for lower profile as well as for smaller floor space.

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